



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Daniel Yap) Group Art No.: 2827
Application No: 10/053,159) Examiner: Thai, Luan C.
Filed: 01/15/2002) Re: Rule 312 Amendment
For: "Precision Electroplated Solder Bumps...") Our Ref: B-3752DIV 619413-2
Date: March 4, 2004

Mail Stop Issue Fee
Commissioner for Patents
POB 1450
Alexandria, VA 22313-1450

Please Enter
LT.
10/4/04

Dear Sir:

This paper is filed in Notice of Allowance dated December 5, 2003.

Amendments to the Claims are reflected in the listing of Claims, which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.